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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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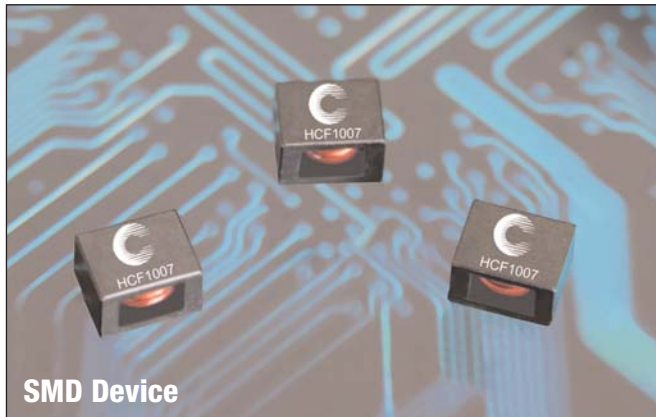
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# High Current, High Frequency, Power Inductors

## HCF1007 Series



### Description

- Halogen free
- 125°C maximum total temperature operation
- 10.3 x 8.1 x 6.65mm surface mount package
- Ferrite core material
- Secure 3 terminal mounting
- High current carrying capacity, low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 0.3µH to 10.0µH
- Current range from 5.3 to 48 Amps
- Frequency range up to 1MHz
- RoHS compliant

### Applications

- Point-of-load modules
- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- Notebook regulators
- Graphics cards and battery power systems
- DCR current sensing

### Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant

### Packaging

- Supplied in tape and reel packaging, 700 parts per 13" diameter reel

### Product Specifications

Part Number <sup>7</sup>	OCL <sup>1</sup> µH ± 20%	FLL <sup>2</sup> Min (µH)	I <sub>rms</sub> <sup>3</sup> Amps	I <sub>sat</sub> <sup>1,4</sup> Amps @25°C	I <sub>sat</sub> <sup>2,5</sup> Amps @125°C	DCR mΩ @20°C	K-factor <sup>6</sup>
HCF1007-R30-R	0.30	0.21	30	48	35	0.90±10%	279.9
HCF1007-R42-R	0.42	0.30	26	45	36	1.30±7%	186.6
HCF1007-R56-R	0.56	0.40	26	36	28	1.30±7%	186.6
HCF1007-R68-R	0.68	0.49	26	29	23	1.30±7%	186.6
HCF1007-1R0-R	1.0	0.72	16	26	21	2.65±6%	139.9
HCF1007-1R5-R	1.5	1.08	13	22	17	4.15±6%	112.0
HCF1007-2R2-R	2.2	1.57	10.7	18	14	6.35±6%	93.30
HCF1007-3R3-R	3.3	2.37	10	14.5	11	7.50±6%	79.97
HCF1007-4R7-R	4.7	3.38	9.4	12	8.9	8.65±6%	69.97
HCF1007-5R6-R	5.6	4.03	9.4	9.4	7.5	8.65±6%	69.97
HCF1007-6R8-R	6.8	4.90	9.4	7.8	6.1	8.65±6%	69.97
HCF1007-100-R	10.0	7.20	9.4	5.3	4.2	8.65±6%	69.97

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V<sub>rms</sub>, 0.0Adc

2 Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, I<sub>sat</sub><sup>1</sup>

3 I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

4 I<sub>sat</sub><sup>1</sup>: Peak current for approximately 20% rolloff at +25°C.

5 I<sub>sat</sub><sup>2</sup>: Peak current for approximately 20% rolloff at +125°C.

6 K-factor: Used to determine B<sub>p-p</sub> for core loss (see graph). B<sub>p-p</sub> = K \* L \* ΔI. B<sub>p-p</sub>: (Gauss), K: (K-factor from table), L: (Inductance in µH), ΔI (peak-to-peak ripple current in amps).

7 Part Number Definition: HCF1007-xxx-R

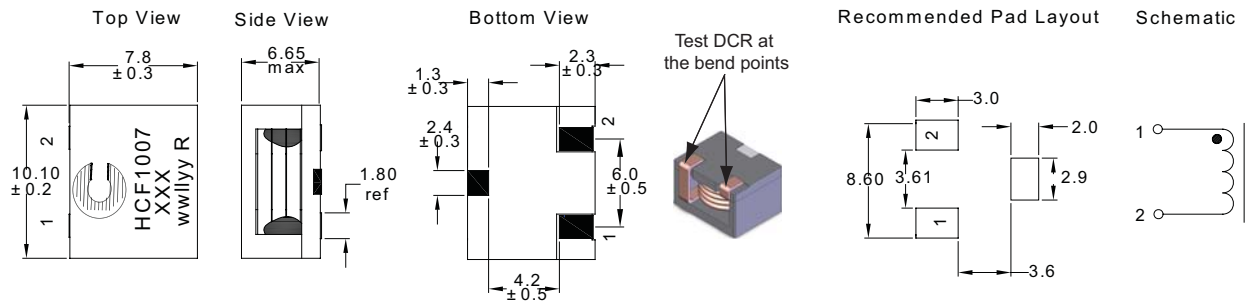
• HCF1007 = Product code and size

• xxx= Inductance value in µH, R = decimal point.

If no "R" is present then third character =# of zeros

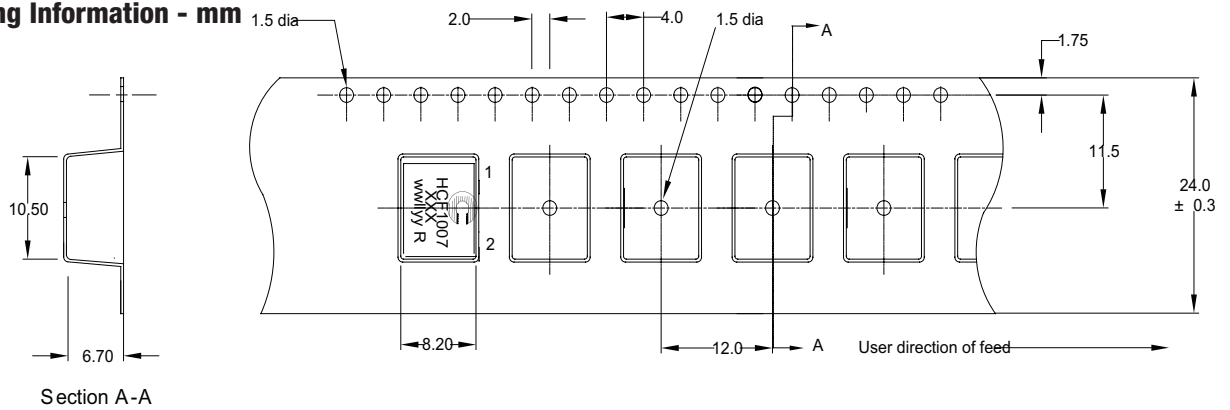
• -R suffix = RoHS compliant

## Dimensions - mm



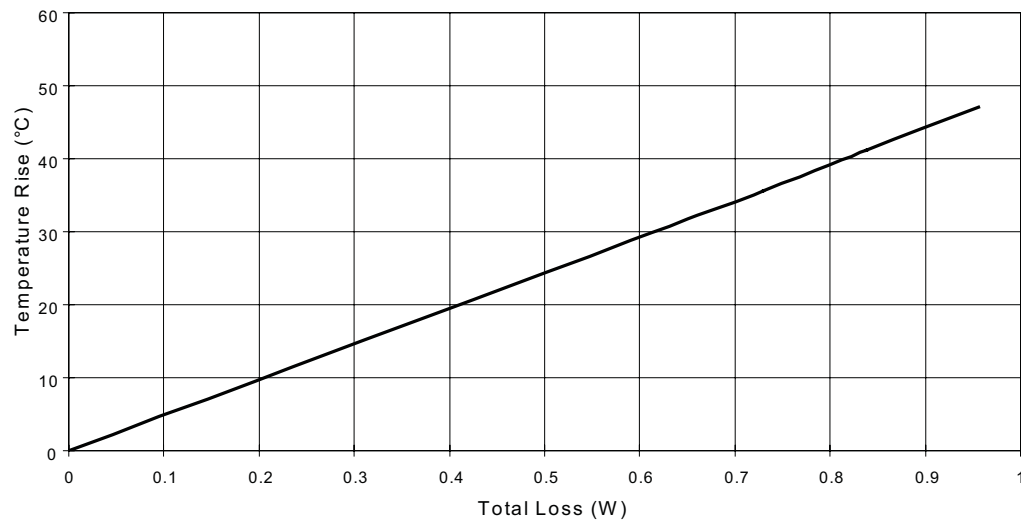
Part Marking: Coiltronics logo HCF1007 xxx = Inductance value in  $\mu\text{H}$ . (R = Decimal point). If no "R" is present, then last character is # of zeros yyllww = Date code R = Revision level

## Packaging Information - mm



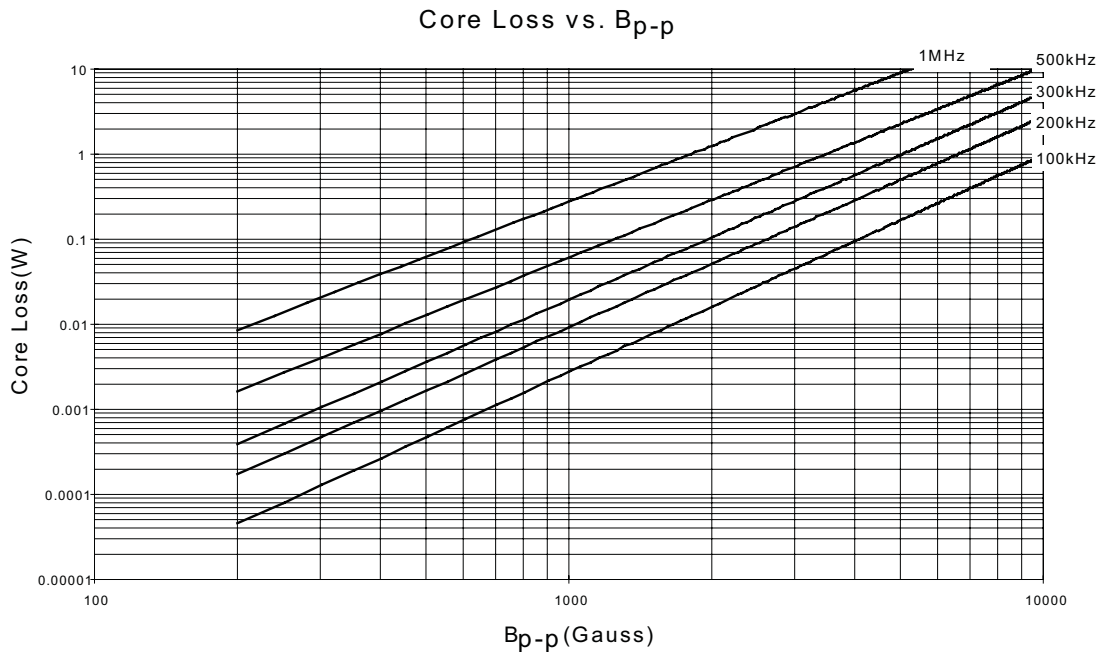
Supplied in tape-and-reel packaging, 700 parts per reel, 13" diameter reel.

## Temperature Rise vs. Total Loss

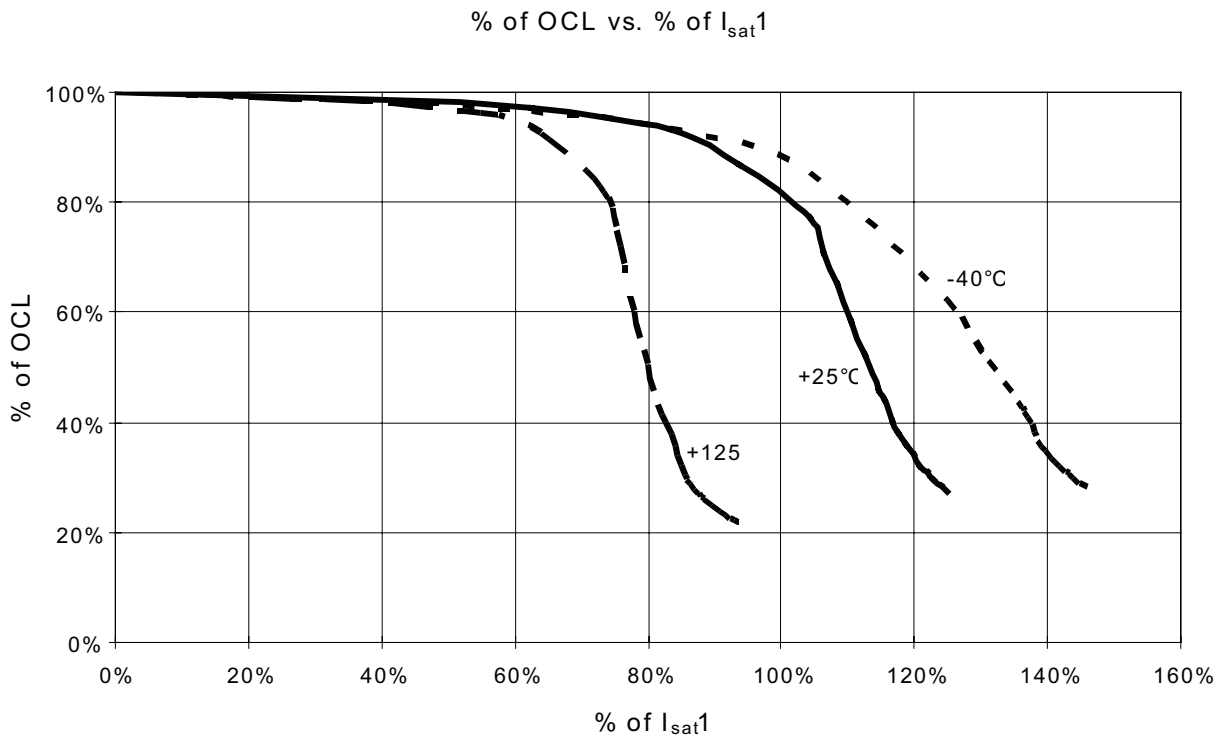




## Core Loss



## Inductance Characteristics



## Solder Reflow Profile

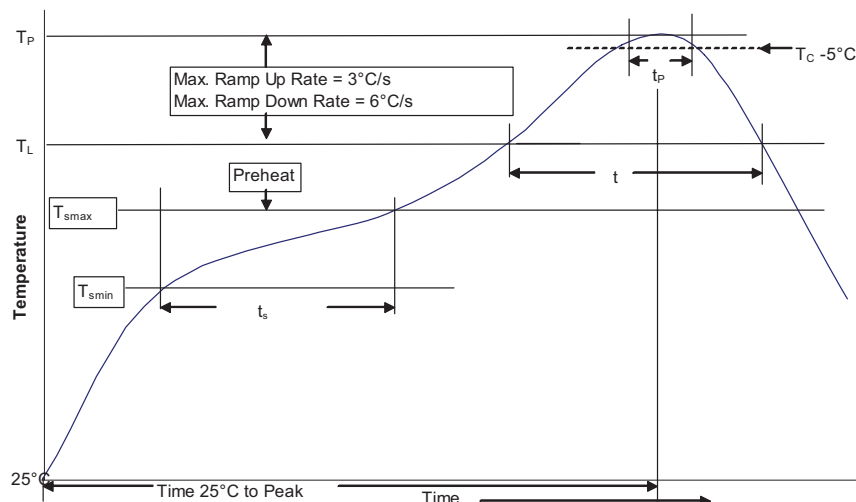


Table 1 - Standard SnPb Solder ( $T_c$ )

Package Thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ $\geq 350$
<2.5mm	235°C	220°C
$\geq 2.5\text{mm}$	220°C	220°C

Table 2 - Lead (Pb) Free Solder ( $T_c$ )

Package Thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ 350 - 2000	Volume $\text{mm}^3$ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. ( $T_{smin}$ )	100°C	150°C
• Temperature max. ( $T_{smax}$ )	150°C	200°C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_p$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_l$ )	183°C	217°C
Time at liquidous ( $t_l$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_c$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

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